CALL FOR PAPER

ICEED 2024

2024 IEEE 13th International Conference on Engineering Education

19 - 20 November 2024 Kanazawa, Japan

HYBRID CONFERENCE



The 2024 IEEE 13th International Conference on Engineering Education (ICEED) is to be held in Kanazawa, Japan from 19th – 20th November 2024. ICEED 2024, a hybrid conference, will be organized by IEEE Malaysia Education Society and co-organized by the Engineering and Technical Research Group (EnTER), School of Electrical Engineering, College of Engineering, Universiti Teknologi MARA, Malaysia, and technically co-sponsored by Kanazawa Institute of Technology, Japan.

TOPIC OF INTEREST

- Accreditation and evaluation
- Engineering Education Reforms
- International Recognition of Qualifications
- New Technologies in Engineering Education
- Industry and Education Collaboration
- Globalization in Education

- Changes and Challenges in Engineering Education
- Distance learning: methods, technologies, and assessment
- Outcome-Based Education
- Linking Academic Knowledge with the Industrial Needs
- Women in Engineering Education

- Research and development in Engineering Education
- Quality Assurance in Engineering Education
- Education in Applied Sciences
- Education in Social Sciences
- Education in Life Science
- Computer and Web based software

PUBLICATION

The Proceedings of ICEED 2024 may be eligible for inclusion in the IEEE Xplore® Digital Library, once they meet the requirements of an IEEE quality review.

WEBSITE



CONTACT US

ICEED2024 Secretariat

School of Electrical Engineering, College of Engineering Universiti Teknologi MARA, 40450 Shah Alam, Selangor, Malaysia email:enter@uitm.edu.my

IMPORTANT DATES

Submission Deadline (Full Paper): 1st May 2024 Early Bird Registration Deadline: 15th September 2024

Final Registration Deadline: 15th October 2024

Notification of Acceptance: 30th June 2024

Final Paper Submission Deadline: 15th October 2024

Conference Date: 19th – 20th November 2024

ORGANIZER





Technical Co-Sponsor

